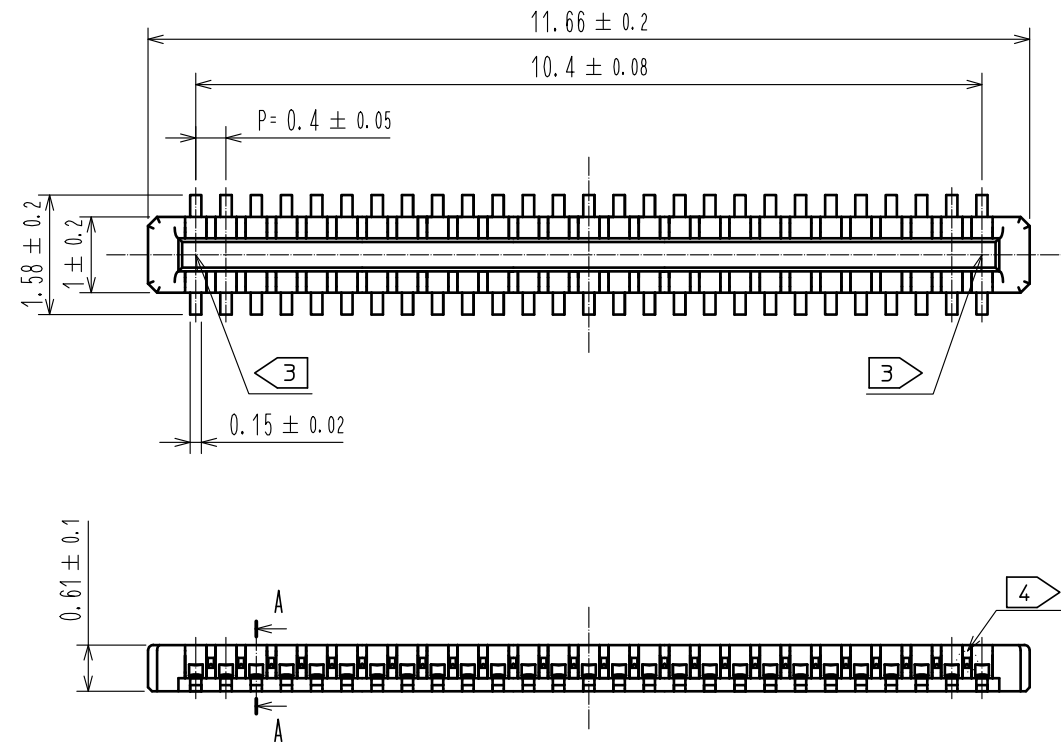
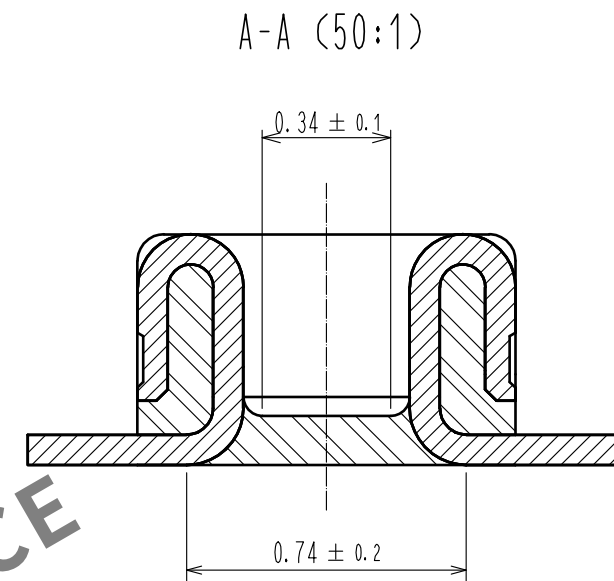
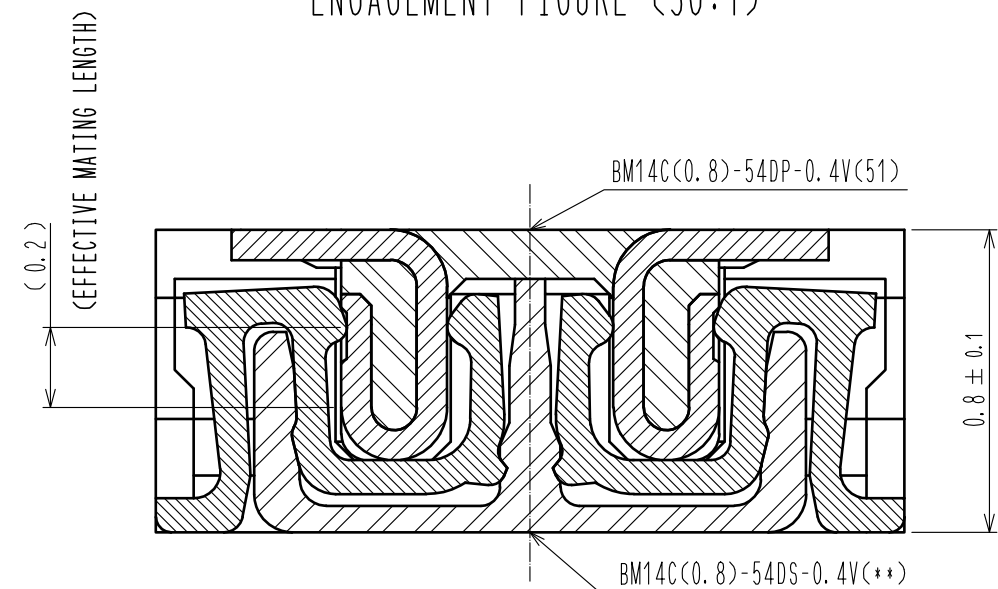




- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD $0.05 \mu\text{m}$ MIN
SMT LEAD : GOLD $0.05 \mu\text{m}$ MIN
UNDERPLATING : NICKEL $1 \mu\text{m}$ MIN
(SURFACE : SEALING)
3. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
4. A PART OF THE WALL COULD BE NOTCHED.

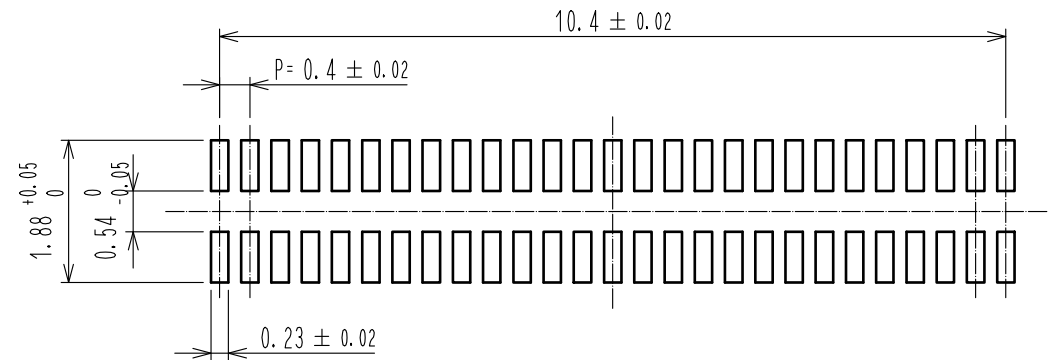


ENGAGEMENT FIGURE (50:1)



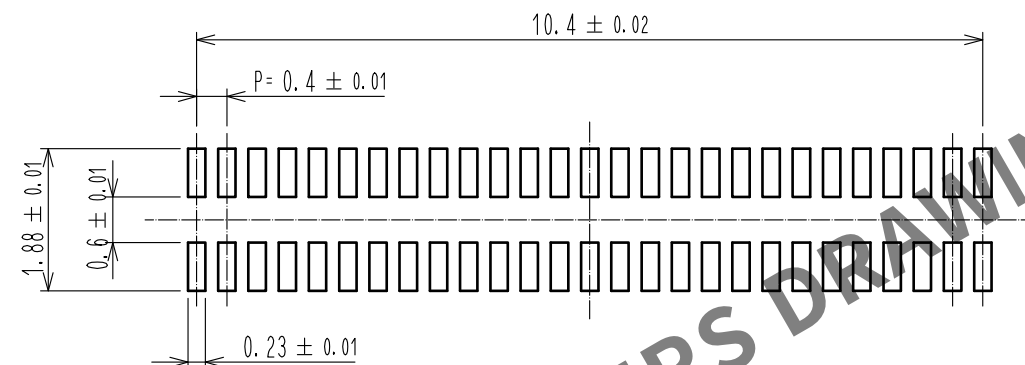
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE 10:1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	16.02.02	DRAWING NO.	EDC-324421-51-01
		CHECKED : TS. MIYAZAKI	16.02.02	PART NO.	BM14C(0.8)-54DP-0.4V(51)
		DESIGNED : SH. HOSODA	16.02.02	CODE NO.	CL684-8031-0-51
		DRAWN : KR. AJITO	16.02.02		
					1/3

◆ RECOMMENDED PCB LAYOUT

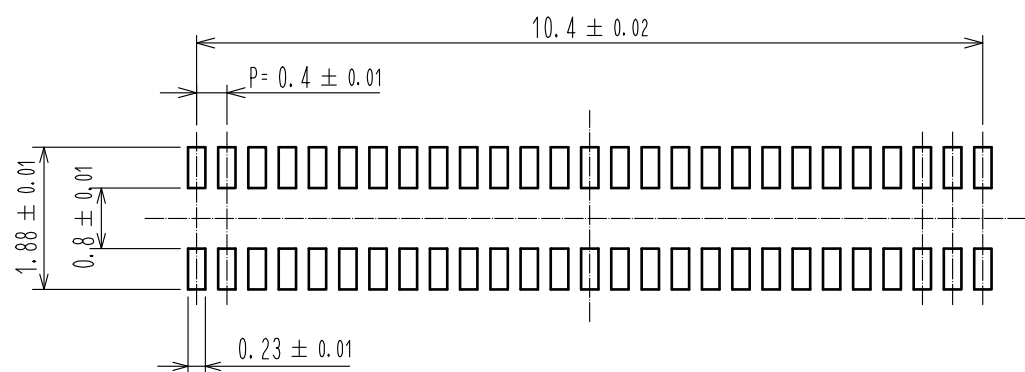


◆ RECOMMENDED METAL MASK DIMENSIONS

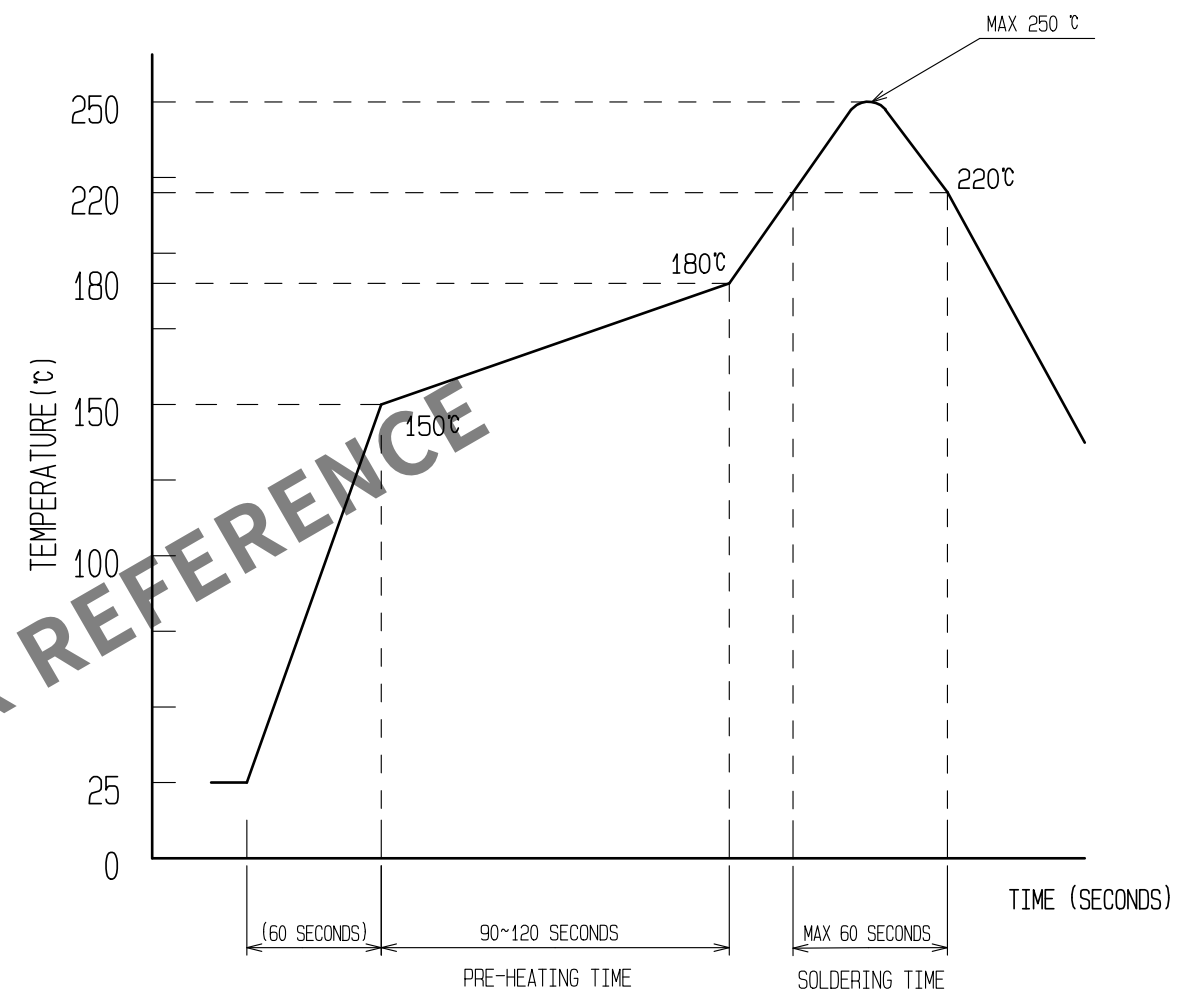
METAL MASK THICKNESS : $100 \mu\text{m}$



METAL MASK THICKNESS : $120 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90~120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC-324421-51-01
PART NO.	BM14C(0.8)-54DP-0.4V(51)
CODE NO.	CL684-8031-0-51

2/3

